1.6x0.8mm SMD CHIP LED LAMP



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

APHK1608TGC

GREEN

Features

- •1.6mmx0.8mm SMT LED, 0.7mm THICKNESS.
- •LOW POWER CONSUMPTION.
- •WIDE VIEWING ANGLE.
- •IDEAL FOR BACK LIGHT AND INDICATOR.
- •VARIOUS COLORS AND LENS TYPES AVAILABLE.
- •PACKAGE: 2000PCS/REEL.
- •RoHS COMPLIANT.

Description

The Green source color devices are made with InGaN on SiC Light Emitting Diode.

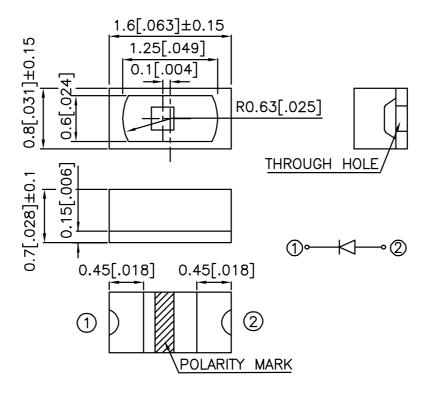
Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or

anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.004")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

 SPEC NO: DSAD1117
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 DATE: MAR/12/2005
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 APPROVED: J. Lu
 CHECKED: Allen Liu
 DRAWN: Y.W.WANG
 ERP:1204000415

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
			Min.	Тур.	201/2
APHK1608TGC	GREEN (InGaN)	WATER CLEAR	70	150	90°

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	500		nm	IF=20mA
λD	Dominant Wavelength	Green	505		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	30		nm	IF=20mA
С	Capacitance	Green	56		pF	VF=0V;f=1MHz
VF	Forward Voltage	Green	3.6	4.4	V	IF=20mA
lr	Reverse Current	Green		10	uA	VR = 5V

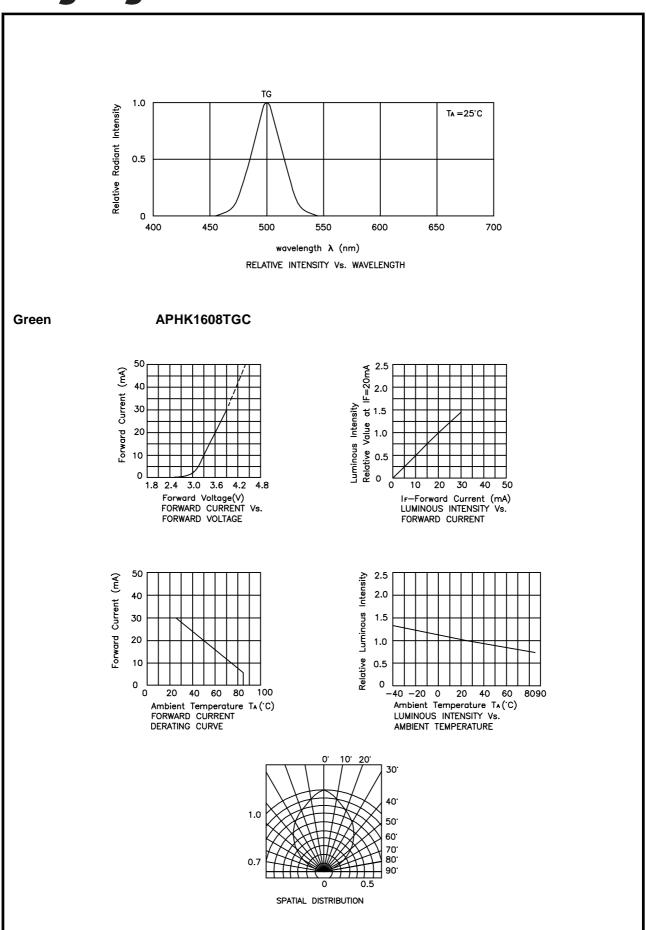
Absolute Maximum Ratings at Ta=25°C

Parameter	Green	Units	
Power dissipation	110	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating/Storage Temperature	-40°C To +85°C		

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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Note:
1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

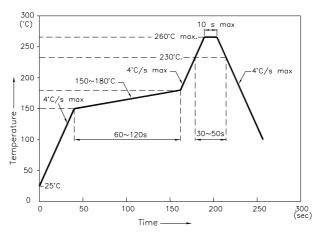


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APHK1608TGC

Reflow Soldering Profile For Lead-free SMT Process.

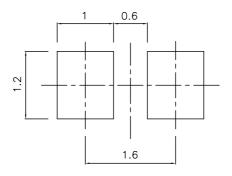


- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
 - 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern

(Units:mm)



Tape Specifications (Units: mm)

TAPE 4.0TYP 2.0TYP 4.0TYP 0.99TYP. 8.0±0.3 1.9±0.1 1.05±0.1 5 MAX. 'SECTION

If there is sorting requirement (eg. forward voltage, luminous intensity or wavelength), the condition as follows:

- 1. Wavelength: +/-1nm (Test condition is based on the sorting standard).
- 2.Luminous intensity: +/-15% (Test condition is based on the sorting standard).
- 3. Forward voltage: +/-0.1V (Test condition is based on the sorting standard).

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